

- Operates at 3-V to 3.6-V V_{CC}
- Free-Running Read and Write Clocks Can Be Asynchronous or Coincident
- Read and Write Operations Synchronized to Independent System Clocks
- Low-Power Advanced CMOS Technology
- Half-Full Flag and Programmable Almost-Full/Almost-Empty Flag
- Bidirectional Configuration and Width Expansion Without Additional Logic
- Input-Ready Flag Synchronized to Write Clock
- Output-Ready Flag Synchronized to Read Clock
- Fast Access Times of 13 ns With a 50-pF Load and All Data Outputs Switching Simultaneously
- Data Rates From 0 to 50 MHz
- Pin Compatible With SN74ACT7803
- Packaged in Shrink Small-Outline 300-mil Package (DL) Using 25-mil Center-to-Center Lead Spacing

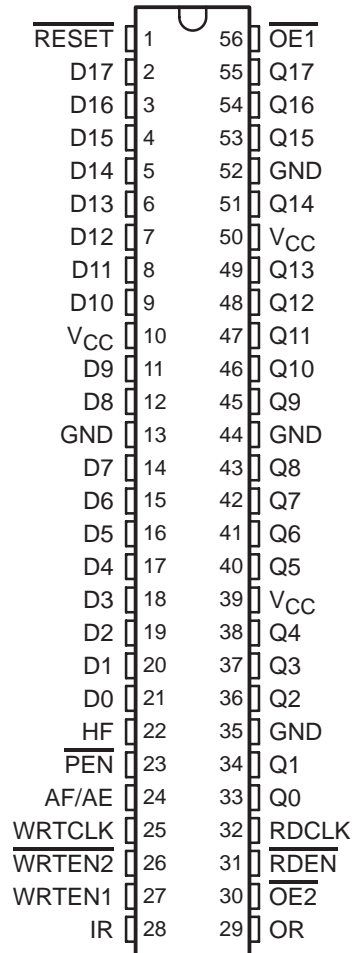
description

The SN74ALVC7803 FIFO is suited for buffering asynchronous data paths at 50-MHz clock rates and 13-ns access times and is designed for 3-V to 3.6-V V_{CC} operation. The 56-pin shrink small-outline (DL) package offers greatly reduced board space over DIP, PLCC, and conventional SOIC packages. Two devices can be configured for bidirectional data buffering without additional logic.

The write clock (WRTCLK) and read clock (RDCLK) should be free running and can be asynchronous or coincident. Data is written to memory on the rising edge of WRTCLK when WRTEN1 is high, $\overline{WRTEN2}$ is low, and input ready (IR) is high. Data is read from memory on the rising edge of RDCLK when \overline{RDEN} , $\overline{OE1}$, and $\overline{OE2}$ are low and output ready (OR) is high. The first word written to memory is clocked through to the output buffer regardless of the \overline{RDEN} , $\overline{OE1}$, and $\overline{OE2}$ levels. The OR flag indicates that valid data is present on the output buffer.

The FIFO can be reset asynchronously to WRTCLK and RDCLK. \overline{RESET} must be asserted while at least four WRTCLK and four RDCLK rising edges occur to clear the synchronizing registers. Resetting the FIFO initializes the IR, OR, and half-full (HF) flags low and the almost-full/almost-empty (AF/AE) flag high. The FIFO must be reset upon power up.

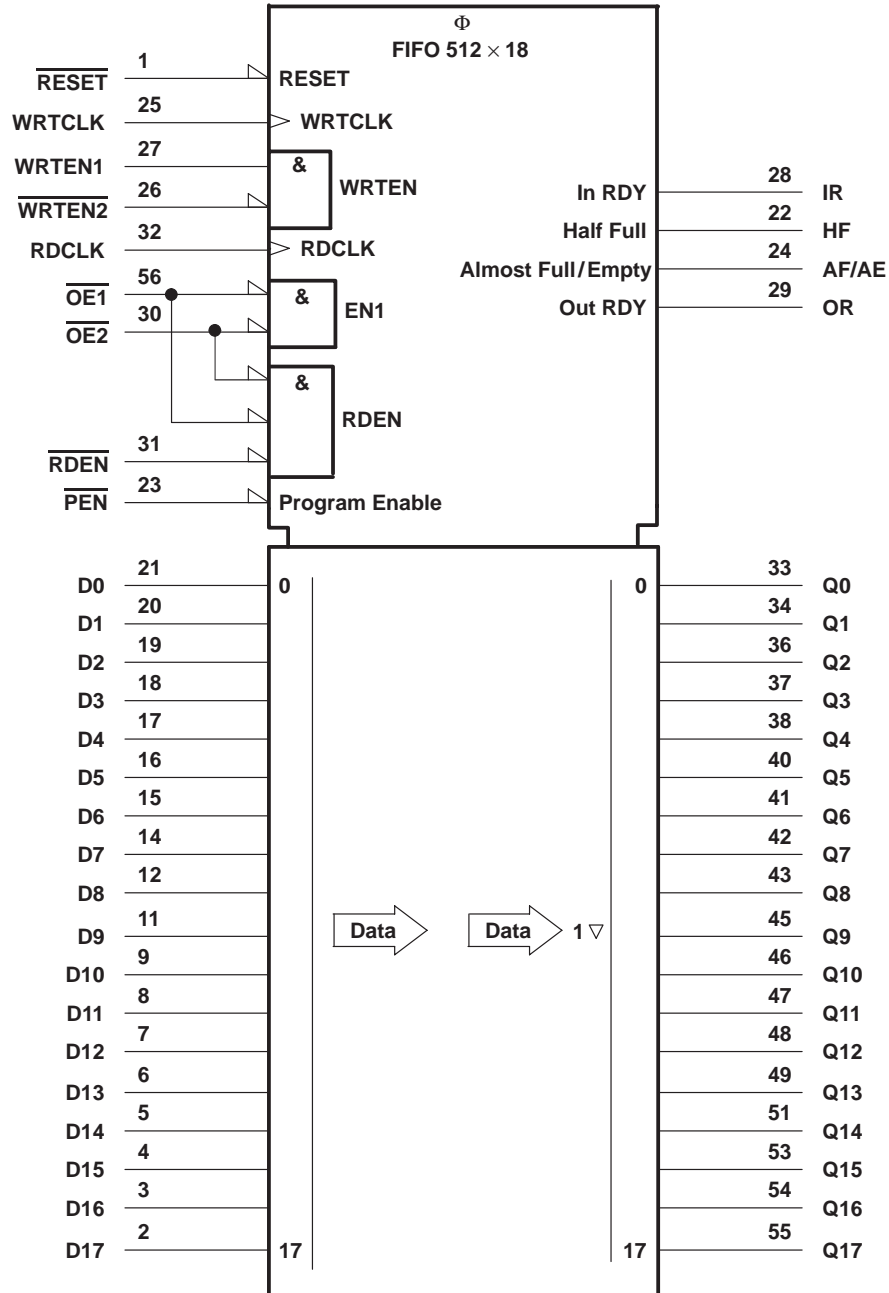
DL PACKAGE
(TOP VIEW)



SN74ALVC7803
512 × 18
CLOCKED FIRST-IN, FIRST-OUT MEMORY

SDAS274 – JANUARY 1995

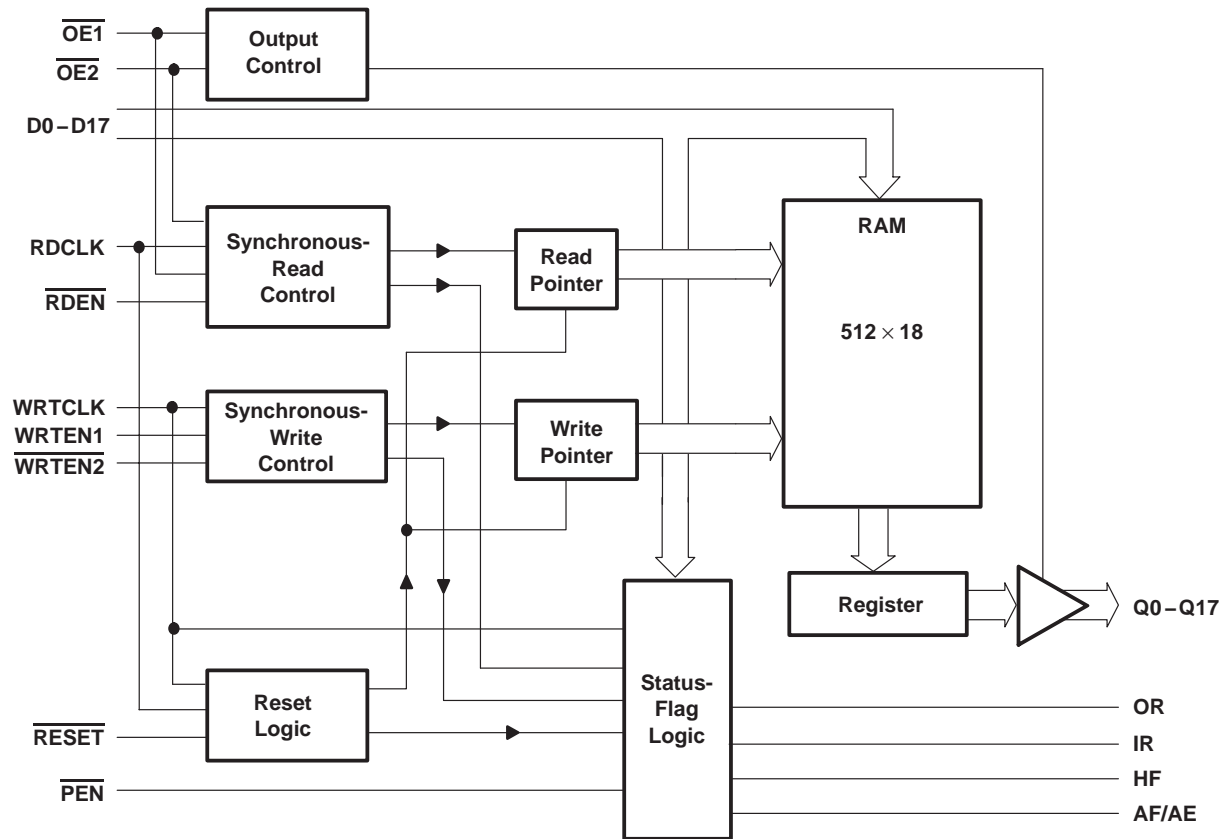
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

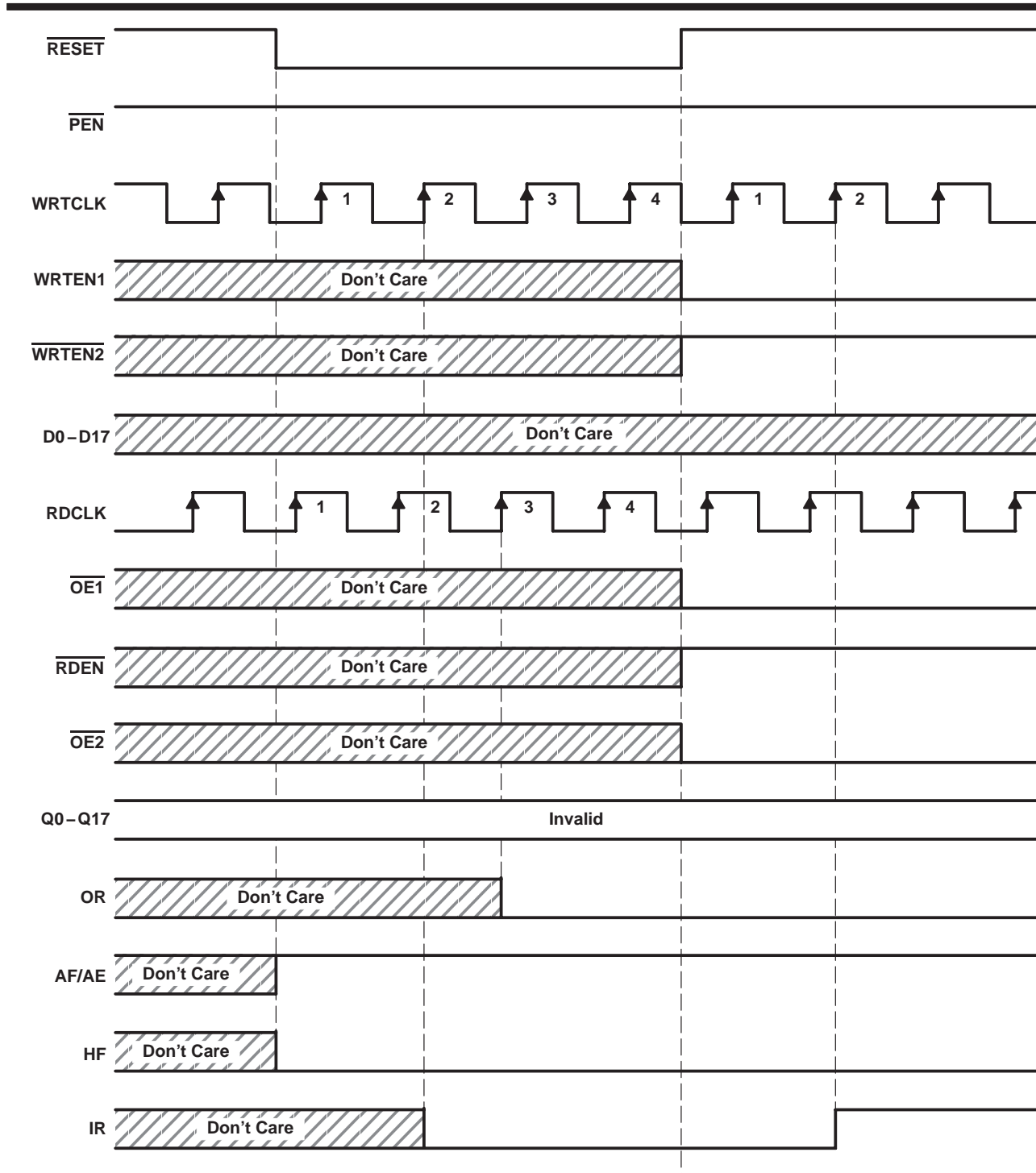


functional block diagram



Terminal Functions

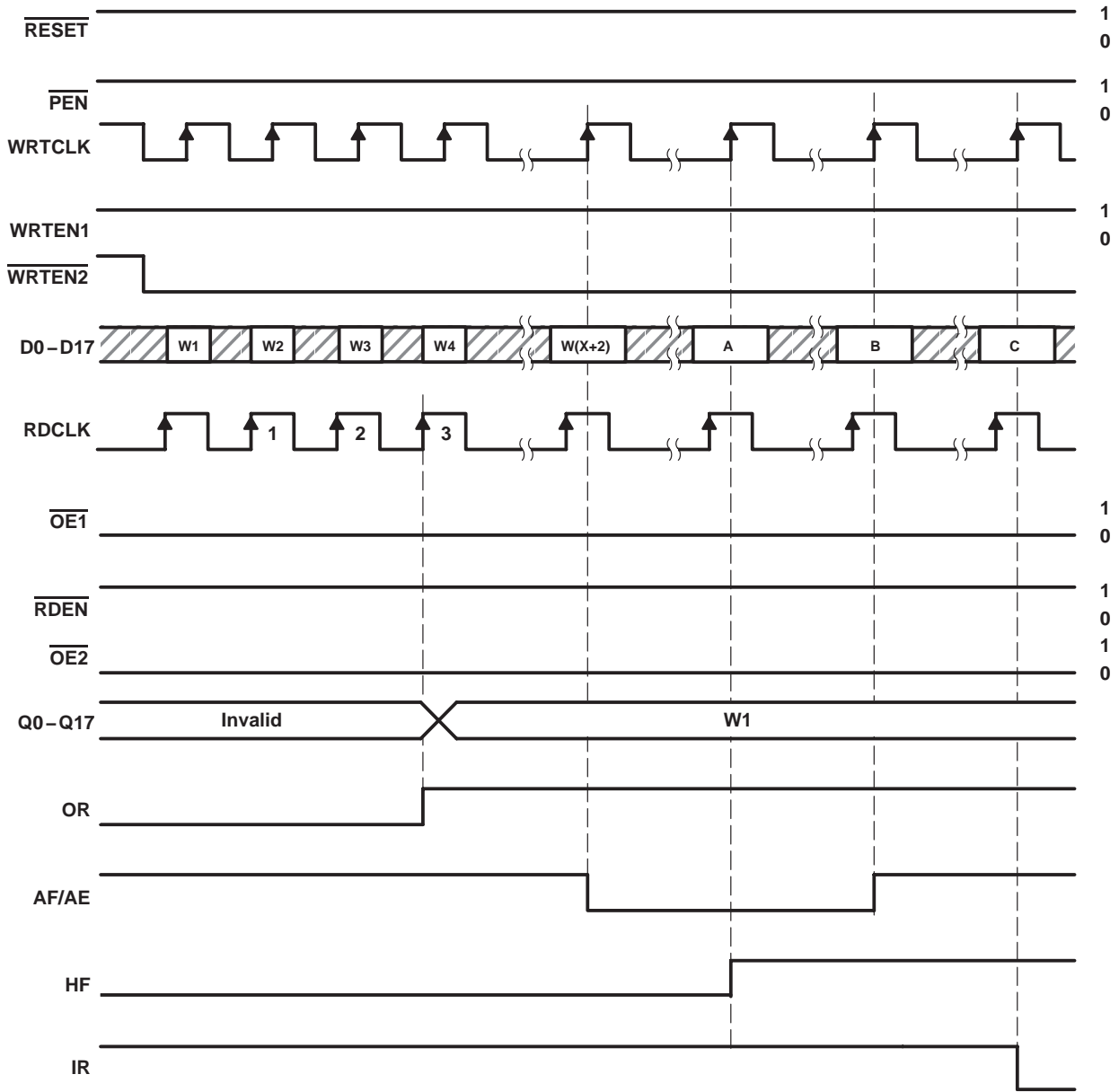
TERMINAL NAME	NO.	I/O	DESCRIPTION
AF/AE	24	O	Almost-full/almost-empty flag. Depth offset values can be programmed for AF/AE, or the default value of 64 can be used for both the almost-empty offset (X) and the almost-full offset (Y). AF/AE is high when memory contains X or less words or (512 minus Y) or more words. AF/AE is high after reset.
D0–D17	21–14, 12–11, 9–2	I	18-bit data input port
HF	22	O	Half-full flag. HF is high when the FIFO memory contains 256 or more words. HF is low after reset.
IR	28	O	Input ready flag. IR is synchronized to the low-to-high transition of WRTCLK. When IR is low, the FIFO is full and writes are disabled. IR is low during reset and goes high on the second low-to-high transition of WRTCLK after reset.
$\overline{OE1}$, $\overline{OE2}$	56, 30	I	Output enables. When $\overline{OE1}$, $\overline{OE2}$, and \overline{RDEN} are low and OR is high, data is read from the FIFO on a low-to-high transition of RDCLK. When either $\overline{OE1}$ or $\overline{OE2}$ is high, reads are disabled and the data outputs are in the high-impedance state.
OR	29	O	Output ready flag. OR is synchronized to the low-to-high transition of RDCLK. When OR is low, the FIFO is empty and reads are disabled. Ready data is present on Q0–Q17 when OR is high. OR is low during reset and goes high on the third low-to-high transition of RDCLK after the first word is loaded to empty memory.
\overline{PEN}	23	I	Program enable. After reset and before the first word is written to the FIFO, the binary value on D0–D7 is latched as an AF/AE offset value when \overline{PEN} is low and WRTCLK is high.
Q0–Q17	33–34, 36–38, 40–43, 45–49, 51, 53–55	O	18-bit data output port. After the first valid write to empty memory, the first word is output on Q0–Q17 on the third rising edge of RDCLK. OR is also asserted high at this time to indicate ready data. When OR is low, the last word read from the FIFO is present on Q0–Q17.
RDCLK	32	I	Read clock. RDCLK is a continuous clock and can be asynchronous or coincident to WRTCLK. A low-to-high transition of RDCLK reads data from memory when $\overline{OE1}$, $\overline{OE2}$, and \overline{RDEN} are low and OR is high. OR is synchronous to the low-to-high transition of RDCLK.
\overline{RDEN}	31	I	Read enable. When \overline{RDEN} , $\overline{OE1}$, and $\overline{OE2}$ are low and OR is high, data is read from the FIFO on the low-to-high transition of RDCLK.
\overline{RESET}	1	I	Reset. To reset the FIFO, four low-to-high transitions of RDCLK and four low-to-high transitions of WRTCLK must occur while \overline{RESET} is low. This sets HF, IR, and OR low and AF/AE high.
WRTCLK	25	I	Write clock. WRTCLK is a continuous clock and can be asynchronous or coincident to RDCLK. A low-to-high transition of WRTCLK writes data to memory when $\overline{WRTEN2}$ is low, $\overline{WRTEN1}$ is high, and IR is high. IR is synchronous to the low-to-high transition of WRTCLK.
$\overline{WRTEN1}$, $\overline{WRTEN2}$	27, 26	I	Write enables. When $\overline{WRTEN1}$ is high, $\overline{WRTEN2}$ is low, and IR is high, data is written to the FIFO on a low-to-high transition of WRTCLK.



Define the AF/AE Flag Using the Default Value of X = Y = 64

Figure 1. Reset Cycle

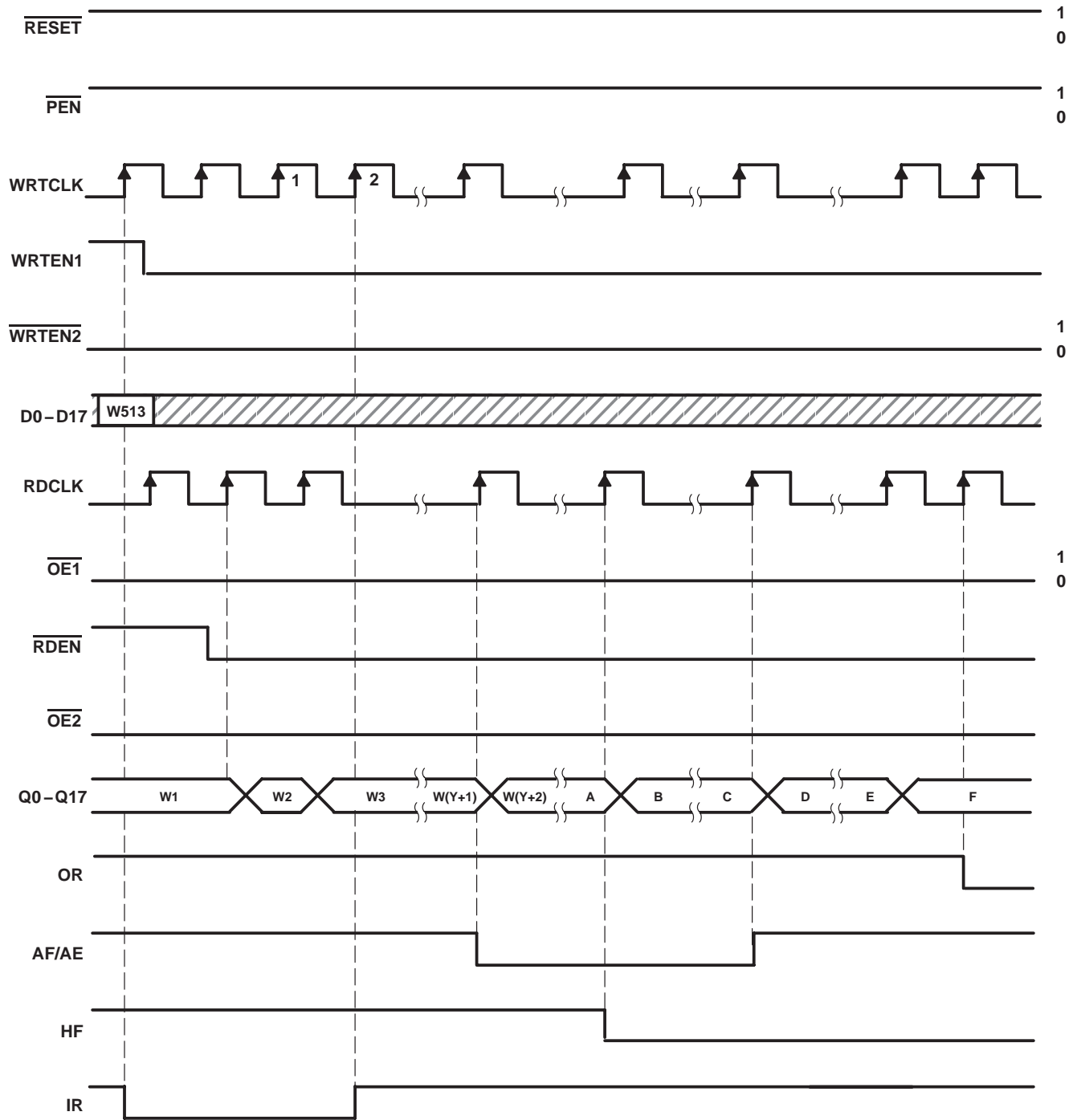
SN74ALVC7803
512 × 18
CLOCKED FIRST-IN, FIRST-OUT MEMORY
SDAS274 – JANUARY 1995



DATA WORD NUMBER FOR FLAG TRANSITIONS

DEVICE	TRANSITION WORD		
	A	B	C
SN74ALVC7803	W257	W((513-Y))	W513

Figure 2. FIFO Write



DATA WORD NUMBERS FOR FLAG TRANSITIONS

DEVICE	TRANSITION WORD					
	A	B	C	D	E	F
SN74ALVC7803	W257	W258	W(512-X)	W(513-X)	W512	W513

Figure 3. FIFO Read

offset values for AF/AE

The AF/AE flag has two programmable limits: the almost-empty offset value (X) and the almost-full offset value (Y). They can be programmed after the FIFO is reset and before the first word is written to memory. If the offsets are not programmed, the default values of $X = Y = 64$ are used. The AF/AE flag is high when the FIFO contains X or less words or (512 minus Y) or more words.

Program enable (\overline{PEN}) should be held high throughout the reset cycle. \overline{PEN} can be brought low only when IR is high. On the following low-to-high transition of WRTCLK, the binary value on D0–D7 is stored as the almost empty offset value (X) and the almost full offset value (Y). Holding \overline{PEN} low for another low-to-high transition of WRTCLK reprograms Y to the binary value on D0–D7 at the time of the second WRTCLK low-to-high transition. When the offsets are being programmed, writes to the FIFO memory are disabled regardless of the state of WRTEN1 and $\overline{WRTEN2}$. A maximum value of 255 can be programmed for either X or Y (see Figure 4). To use the default values of $X = Y = 64$, \overline{PEN} must be held high.

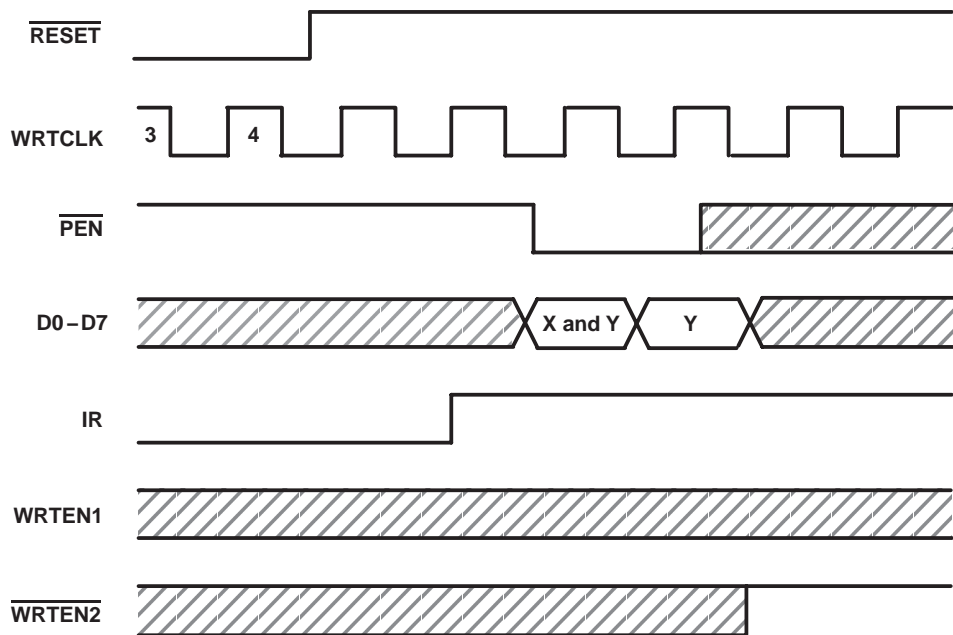


Figure 4. Programming X and Y Separately

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	-0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	-0.5 V to 4.6 V
Output voltage range, V_O (see Notes 1 and 2)	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	-50 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	± 50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 50 mA
Continuous current through V_{CC} or GND	± 100 mA
Voltage applied to a disabled 3-state output	3.6 V
Operating free-air temperature range, T_A	0°C to 70°C
Storage temperature range	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings can be exceeded if the input and output clamp current ratings are observed.
2. This value is limited to 4.6 V maximum.

recommended operating conditions

		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 3.3 V ± 0.3 V		UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX		
V _{IH}	High-level input voltage	2		2		2		V	
V _{IL}	Low-level input voltage	0.8		0.8		0.8		V	
I _{OH}	High-level output current, Q outputs, flags	V _{CC} = 3 V		-8		-8		mA	
I _{OL}	Low-level output current, Q outputs, flags	V _{CC} = 3 V		16		16			
f _{clock}	Clock frequency	50		40		25		MHz	
t _w	Pulse duration	D0–D17 high or low	9		10		14		ns
		WRTCLK high or low	7		8		12		
		RDCLK high or low	7		8		12		
		PEN low	9		9		12		
		WRTEN1 high, WRTEN2 low	8		8		12		
		OE1, OE2 low	9		9		12		
		RDEN low	8		8		12		
t _{su}	Setup time	D0–D17 before WRTCLK↑	5		5		5		ns
		WRTEN1, WRTEN2 before WRTCLK↑	5		5		5		
		OE1, OE2 before RDCLK↑	5		6		6		
		RDEN before RDCLK↑	5		5		7		
		Reset: RESET low before first WRTCLK↑ and RDCLK↑†	6		6		6		
		PEN before WRTCLK↑	6		6		6		
t _h	Hold time	D0–D17 after WRTCLK↑	0		0		0		ns
		WRTEN1, WRTEN2 after WRTCLK↑	0		0		0		
		OE1, OE2, RDEN after RDCLK↑	0		0		0		
		Reset: RESET low after fourth WRTCLK↑ and RDCLK↑†	2		2		2		
		PEN low after WRTCLK↑	2		2		2		
T _A	Operating free-air temperature	0 70		0 70		0 70		°C	

† To permit the clock pulse to be utilized for reset purposes



SN74ALVC7803

512 × 18

CLOCKED FIRST-IN, FIRST-OUT MEMORY

SDAS274 – JANUARY 1995

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
V _{IK}		V _{CC} = 3 V,	I _{IK} = -18 mA			-1.2	V
V _{OH}	Flags	V _{CC} = MIN to MAX,	I _{OH} = -100 μA	V _{CC} - 0.2			V
	Q outputs	V _{CC} = 3 V,	I _{OH} = -8 mA	2.4			
V _{OL}	Flags, Q outputs	V _{CC} = MIN to MAX,	I _{OL} = 100 μA			0.2	V
	Flags	V _{CC} = 3 V,	I _{OL} = 8 mA			0.4	
	Q outputs	V _{CC} = 3 V,	I _{OL} = 16 mA			0.55	
I _I		V _{CC} = 3.6 V,	V _I = V _{CC} or GND			±5	μA
I _{OZ}		V _{CC} = 3.6 V,	V _O = V _{CC} or GND			±10	μA
I _{CC}		V _I = V _{CC} or 0,	I _O = 0			40	μA
ΔI _{CC} §		V _{CC} = 3.6 V, One input at V _{CC} - 0.6 V	Other inputs at V _{CC} or GND,			500	μA
C _i		V _{CC} = 3.3 V,	V _I = V _{CC} or GND, f = 1 MHz		2.5		pF
C _o		V _{CC} = 3.3 V,	V _O = V _{CC} or GND, f = 1 MHz		5.5		pF

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

§ This is the supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 7)

PARAMETER	FROM (OUTPUT)	TO (INPUT)	V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}	WRTCLK or RDCLK		50		40		25		MHz
t _{pd}	RDCLK↑	Any Q	4	13	4	15	4	20	ns
t _{pd} ¶									
t _{pd}	WRTCLK↑	IR	3	11	3	13	3	15	ns
t _{pd}	RDCLK↑	OR	3	11	3	13	3	15	ns
t _{pd}	WRTCLK↑	AF/AE	7	19	7	21	7	23	ns
t _{pd}	RDCLK↑	AF/AE	7	19	7	21	7	23	ns
t _{PLH}	WRTCLK↑	HF	7	17	7	19	7	21	ns
t _{PHL}	RDCLK↑		7	18	7	20	7	22	
t _{PLH}	RESET low	AF/AE	2	11	2	13	2	15	ns
t _{PHL}		HF	2	12	2	14	2	16	
t _{en}	OE1, OE2	Any Q	2	11	2	11	2	14	ns
t _{dis}			2	11	2	14	2	14	

¶ This parameter is measured with a 50-pF load (see Figure 7).

operating characteristics, V_{CC} = 3.3 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	Outputs enabled C _L = 50 pF, f = 5 MHz	53	pF



APPLICATION INFORMATION

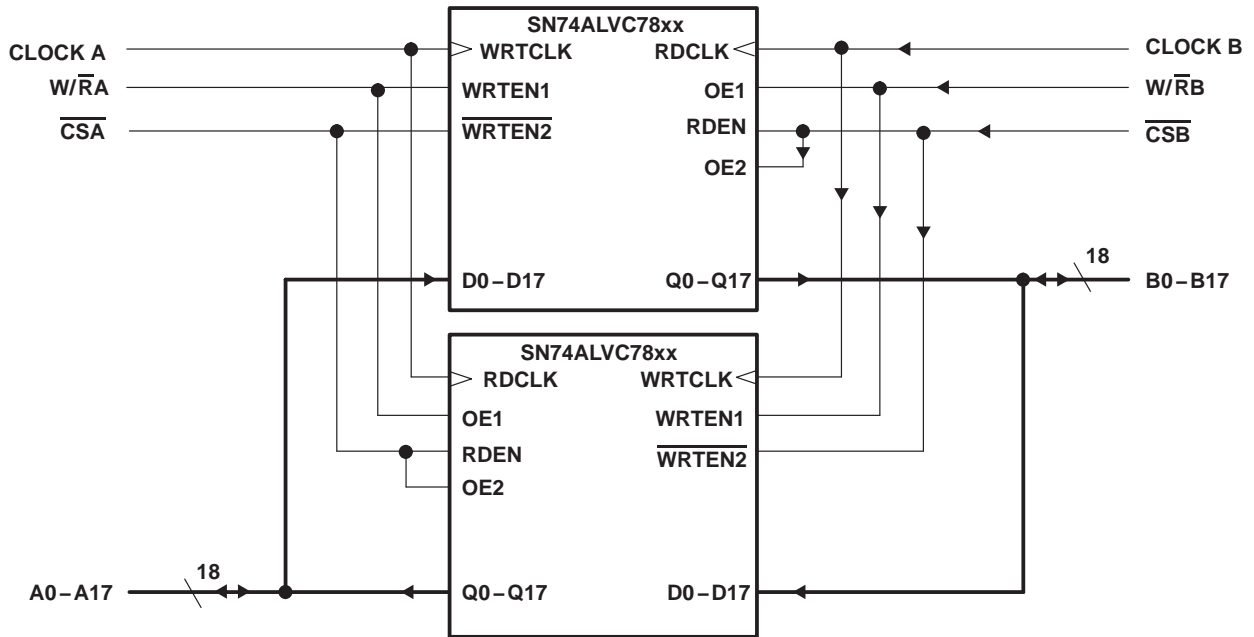


Figure 5. Bidirectional Configuration

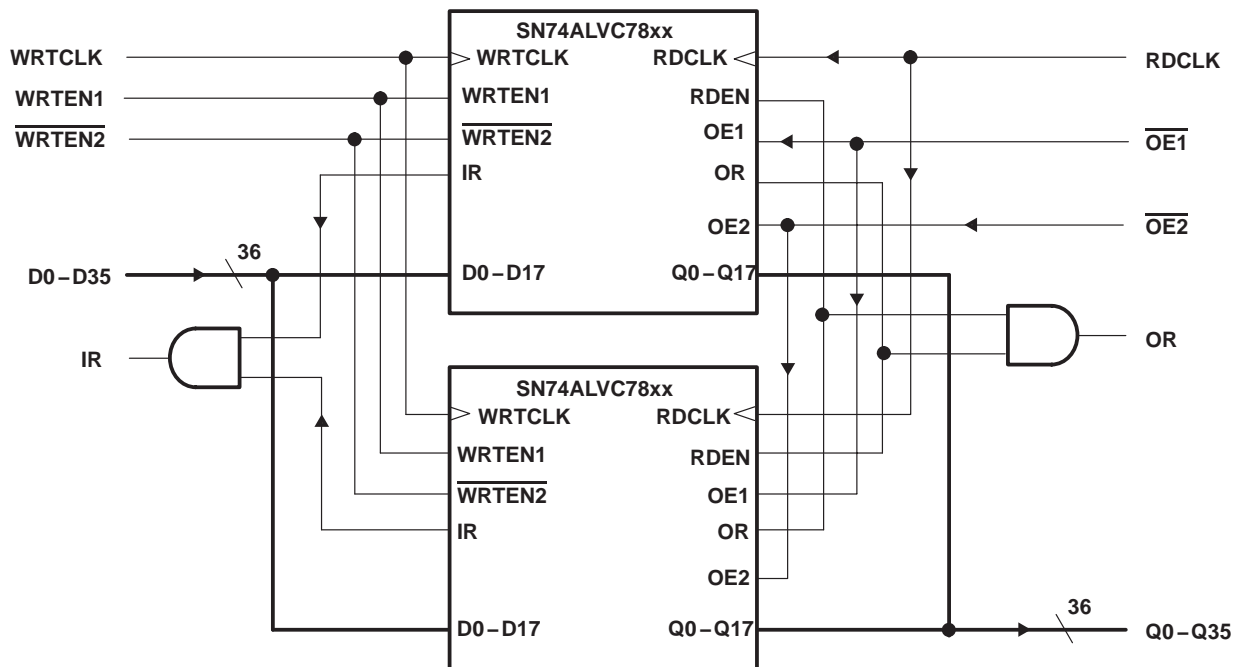


Figure 6. Word-Width Expansion: 512 × 36 Bit , 256 × 36 Bit, and 64 × 36 Bit

TYPICAL CHARACTERISTICS

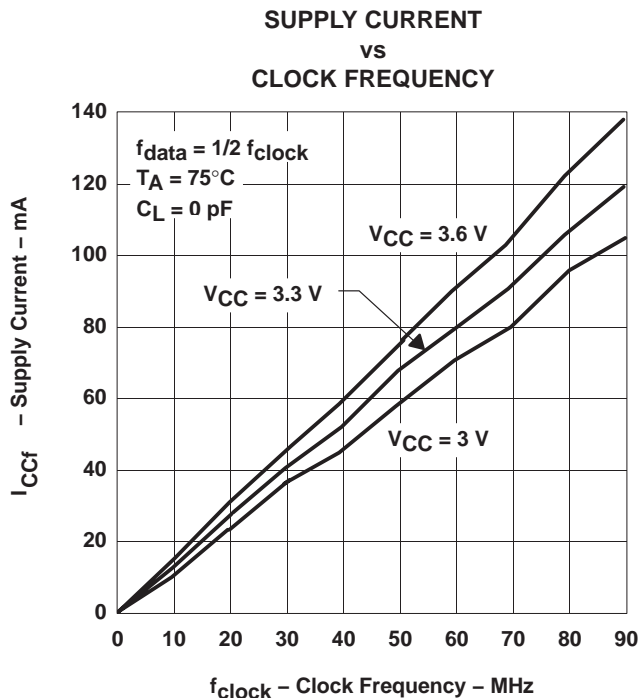


Figure 7

calculating power dissipation

With I_{CCf} taken from Figure 7, the dynamic power (P_d), based on all data outputs changing states on each read, can be calculated by using:

$$P_d = V_{CC} \times [I_{CC(f)} + (N \times \Delta I_{CC} \times dc)] + \Sigma(C_L \times V_{CC}^2 \times f_o)$$

A more accurate total power (P_T) can be calculated if quiescent power (P_q) is also taken into consideration. Quiescent power (P_q) can be calculated using:

$$P_q = V_{CC} \times [I_{CCi} + (N \times \Delta I_{CC} \times dc)]$$

Total power would be:

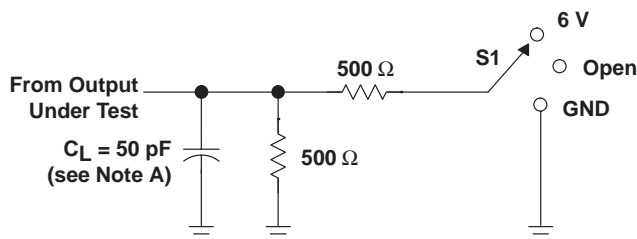
$$P_T = P_d + P_q$$

The above equations provide worst-case power calculations.

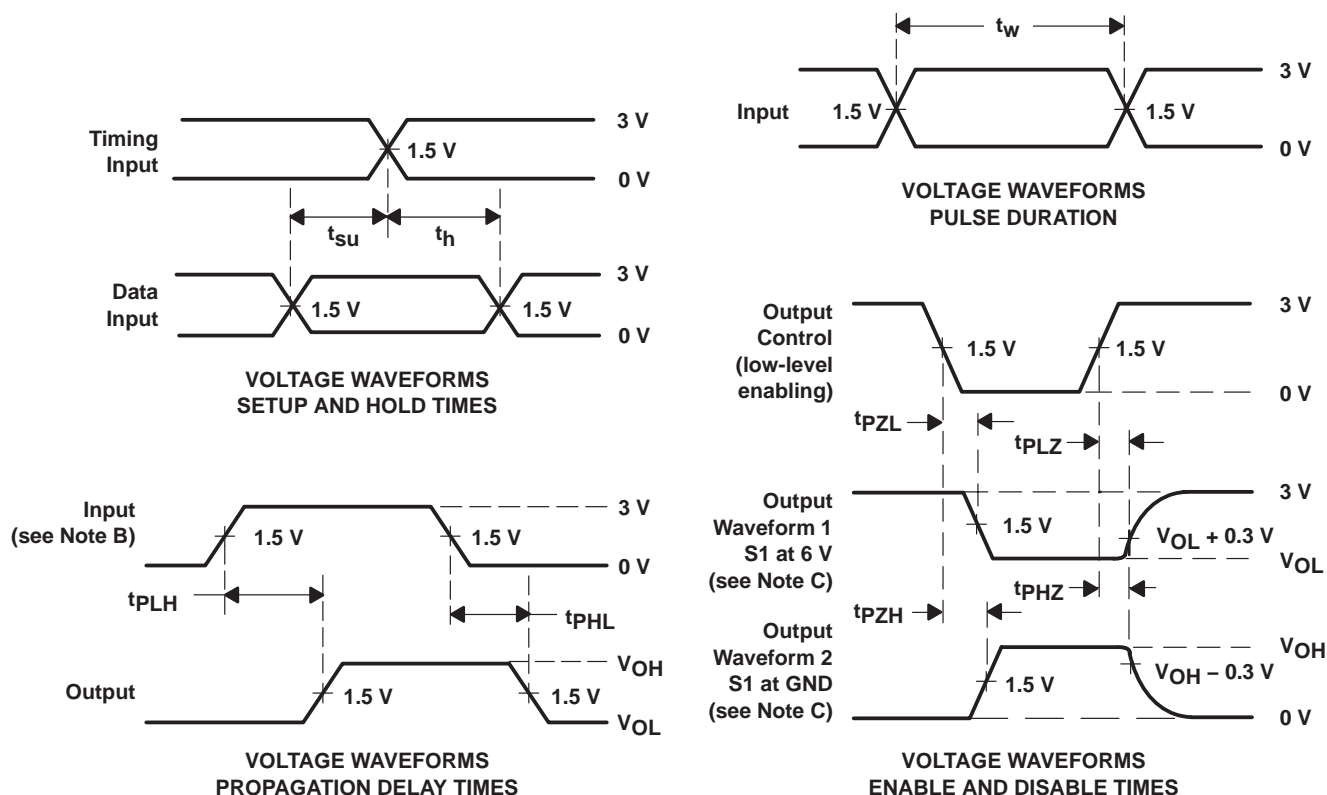
Where:

- N = number of inputs driven by TTL levels
- ΔI_{CC} = increase in power supply current for each input at a TTL high level
- dc = duty cycle of inputs at a TTL high level of 3.4 V
- C_L = output capacitance load
- f_o = switching frequency of an output
- I_{CCi} = idle current, supply current when FIFO is idle $\approx pF \times f_{clock} = 0.2 \times f_{clock}$
(current is due to free-running clocks)
- pF = power factor (the slope of idle current versus clock frequency).
- I_{CCf} = active current, supply current when FIFO is transferring data

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT FOR OUTPUTS



- NOTES: A. C_L includes probe and jig capacitance.
 B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

3-STATE OUTPUTS (ANY Q)

PARAMETER		R1, R2	C_L^\dagger	S1
t_{en}	t_{PZH}	500 Ω	50 pF	GND
	t_{PZL}			6 V
t_{dis}	t_{PHZ}	500 Ω	50 pF	GND
	t_{PLZ}			6 V
t_{pd}	t_{PLH}/t_{PHL}	500 Ω	50 pF	Open

† Includes probe and test-fixture capacitance

Figure 8. Standard CMOS Outputs (FULL, EMPTY, HF, AF/AE)

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74ALVC7803-20DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALVC7803-20	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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MECHANICAL DATA

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MO-118

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